	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	70848	34/$.ccls. 134/$.ccls.	USPAT; EPO; JPO	2004/03/01			0
2	BRS	344	(34/$.ccls. 134/$.ccls.) and (substrate wafer) and vacuum and cassette	USPAT; EPO; JPO	2004/03/01 11:45			0
3	BRS	2	((34/$.ccls. 134/$.ccls.) and (substrate wafer) and vacuum and cassette) and (transfer with cassette) and (original with cassette with return)	USPAT; EPO; JPO	2004/03/01 11:46			0
4	BRS	50	((34/$.ccls. 134/$.ccls.) and (substrate wafer) and vacuum and cassette) and (transfer with cassette) and (original with cassette)	USPAT; EPO; JPO	2004/03/01 11:49			0
5	BRS	43	((34/$.ccls. 134/$.ccls.) and (substrate wafer) and vacuum and cassette) and (transfer with cassette) and (original with cassette) and dummy	USPAT; EPO; JPO	2004/03/02 09:14			0
6	BRS	1	"4923584".PN.	USPAT	2004/03/01			0
7	BRS	1	4923584.pn. and (plasma dummy)	USPAT; EPO; JPO	2004/03/01			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
8	BRS	1	(((34/$.ccls. 134/$.ccls.) and (substrate wafer) and vacuum and cassette) and (transfer with cassette) and (original with cassette) and dummy) not kato	USPAT; EPO; JPO	2004/03 /02 09:15			0
9	BRS	43	(((34/$.ccls. 134/$.ccls.) and (substrate wafer) and vacuum and cassette) and (transfer with cassette) and (original with cassette) and dummy	USPAT; EPO; JPO	2004/03 /02 09:16			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
10	BRS	48	("3652444" | "3981791" | "4138306" | "4226897" | "4311427" | "4313783" | "4313815" | "4318767" | "4449885" | "4457661" | "4534314" | "4563240" | "4576698" | "4634331" | "4643629" | "4705951" | "4715764" | "4824309" | "4836733" | "4836905" | "4851101" | "4895107" | "4902934" | "4903937" | "4909695" | "4911597" | "4915564" | "4917556" | "4923584" | "4924890" | "4936329" | "4951601" |	USPAT	2004/03/02 09:15			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
11	BRS	1	(("3652444" | "3981791" | "4138306" | "4226897" | "4311427" | "4313783" | "4313815" | "4318767" | "4449885" | "4457661" | "4534314" | "4563240" | "4576698" | "4634331" | "4643629" | "4705951" | "4715764" | "4824309" | "4836733" | "4836905" | "4851101" | "4895107" | "4902934" | "4903937" | "4909695" | "4911597" | "4915564" | "4917556" | "4923584" | "4924890" | "4936329" | "4951601" |	USPAT; EPO; JPO	2004/03 /02 09:16			0
12	BRS	10	(34/$.ccls. 134/$.ccls.) and ((substrate wafer) with dummy) and @py<1990	USPAT; EPO; JPO	2004/03 /02 09:28			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
13	BRS	13	(34/$.ccls. 134/$.ccls.) and ((substrate wafer) with dummy) and @py<1993	USPAT; EPO; JPO	2004/03/02 09:28			0
14	BRS	3	((34/$.ccls. 134/$.ccls.) and ((substrate wafer) with dummy) and @py<1993) not ((34/$.ccls. 134/$.ccls.) and ((substrate wafer) with dummy) and @py<1990)	USPAT; EPO; JPO	2004/03/02 09:30			0
15	BRS	63	kato and (wafer substrate) and 34/$.ccls.	USPAT; EPO; JPO	2004/03/02 09:30			0
16	BRS	14	(kato and (wafer substrate) and 34/$.ccls.) and kathryn	USPAT; EPO; JPO	2004/03/02 09:31			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
17	BRS	49	("3652444" | "3981791" | "4138306" | "4226897" | "4311427" | "4313783" | "4313815" | "4318767" | "4449885" | "4457661" | "4534314" | "4563240" | "4576698" | "4634331" | "4643629" | "4705951" | "4715764" | "4824309" | "4836733" | "4836905" | "4851101" | "4895107" | "4902934" | "4903937" | "4909695" | "4911597" | "4915564" | "4917556" | "4923584" | "4924890" | "4936329" | "4951601" |	USPAT	2004/03 /02 09:31			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
18	BRS	3	(("3652444" | "3981791" | "4138306" | "4226897" | "4311427" | "4313783" | "4313815" | "4318767" | "4449885" | "4457661" | "4534314" | "4563240" | "4576698" | "4634331" | "4643629" | "4705951" | "4715764" | "4824309" | "4836733" | "4836905" | "4851101" | "4895107" | "4902934" | "4903937" | "4909695" | "4911597" | "4915564" | "4917556" | "4923584" | "4924890" | "4936329" | "4951601" |	USPAT; EPO; JPO	2004/03 /02 09:31		0	

	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
1	US 5169407 A	1992 1208	Method of determining end of cleaning of semiconductor manufacturing apparatus	29/25.01	134/1; 204/192.33; 204/298.32; 216/59	Mase, Yasukazu et al.
2	US 5016663 A	1991 0521	Method of determining end of cleaning of semiconductor manufacturing apparatus	134/1	134/1.1; 204/192.33; 204/298.32;	Mase, Yasukazu et al.
3	US 4827867 A	1989 0509	Resist developing apparatus	118/64	118/320; 118/326; 118/52; 118/667; 134/105; 134/200; 134/902; 165/156; 165/169; 165/289; 165/64; 427/422	Takei, Toshitaka et al.

	Document ID	Issue Date	Title	Curre nt OR	Curren t XRef	Inventor
4	US 4597989 A	1986 0701	Method of depositing silicon films with reduced structural defects	427/9 9	134/22. 18; 134/37; 438/68 4; 438/75 8; 438/79 1; 438/90 5	Wonsowicz, Casimir J. et al.
5	US 4529474 A	1985 0716	Method of cleaning apparatus for forming deposited film	134/1. 1	118/50. 1; 118/62 0; 118/71 5; 134/1; 204/19 2.32; 204/29 8.33; 216/79; 427/58 5	Fujiyama, Yasutomo et al.
6	US 4512812 A	1985 0423	Method for reducing phosphorous contamination in a vacuum processing chamber	134/2 1	134/22. 18; 134/30; 134/31; 134/42	Liebert, Reuel B. et al.
7	US 4412388 A	1983 1101	Method for drying semiconductor substrates	34/25 9	118/62 0; 219/69 0; 34/239	Takagi, Mikio et al.

	Document ID	Issue Date	Title	Curren t OR	Curren t XRef	Inventor
8	US 4201579 A	1980 0506	Method for removing photoresist by hydrogen plasma	430/3 23	134/1; 134/1.2 ; 204/19 2.32; 216/59; 257/E2 1.249; 257/E2 1.256; 315/11 1.21; 430/32 9; 430/49	Robinson, Frederick J. et al.
9	JP 03064916 A	1991 0320	WAFER WASHING METHOD		134/90 2	MIYAMOT O, YASUNOR I
10	JP 63185032 A	1988 0730	ETCHING APPARATUS FOR SILICON SUBSTRATE		134/41	NONAKA, TSUTOMU
11	JP 62023116 A	1987 0131	WET SEMICONDUCTOR MANUFACTURING EQUIPMENT		34/58	EJIRI, IWAO
12	JP 59229822 A	1984 1224	ETCHING APPARATUS		134/1; 257/E2 1.215	NITTA, TAKEHISA
13	JP 58009325 A	1983 0119	SELF-ROTATIONAL WAFER DRYER		34/58; 34/108	OKUMUR A, KATSUYA